

# 2SK2553(L), 2SK2553(S)

Silicon N Channel MOS FET  
High Speed Power Switching

## HITACHI

ADE-208-357H (Z)  
9th. Edition  
Feb. 1999

### Application

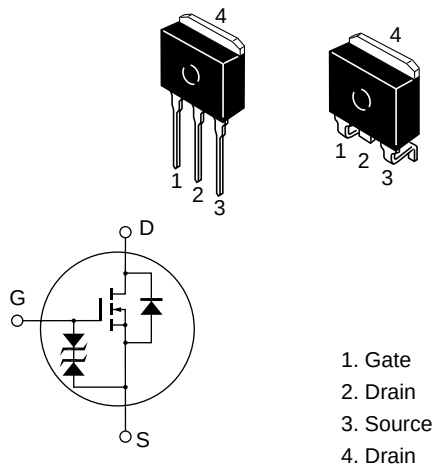
High speed power switching

### Features

- Low on-resistance
- $R_{DS(on)} = 7 \text{ m}\Omega$  typ.
- High speed switching
- 4 V gate drive device can be driven from 5 V source

### Outline

LDPAK



Absolute Maximum Ratings (Ta = 25°C)

| Item                                      | Symbol                                  | Ratings     | Unit |
|-------------------------------------------|-----------------------------------------|-------------|------|
| Drain to source voltage                   | V <sub>DSS</sub>                        | 60          | V    |
| Gate to source voltage                    | V <sub>GSS</sub>                        | ±20         | V    |
| Drain current                             | I <sub>D</sub>                          | 50          | A    |
| Drain peak current                        | I <sub>D(pulse)</sub> <sup>Note 1</sup> | 200         | A    |
| Body to drain diode reverse drain current | I <sub>DR</sub>                         | 50          | A    |
| Avalanche current                         | I <sub>AP</sub> <sup>Note 3</sup>       | 45          | A    |
| Avalanche energy                          | E <sub>AR</sub> <sup>Note 3</sup>       | 174         | mJ   |
| Channel dissipation                       | P <sub>ch</sub> <sup>Note 2</sup>       | 75          | W    |
| Channel temperature                       | T <sub>ch</sub>                         | 150         | °C   |
| Storage temperature                       | T <sub>stg</sub>                        | −55 to +150 | °C   |

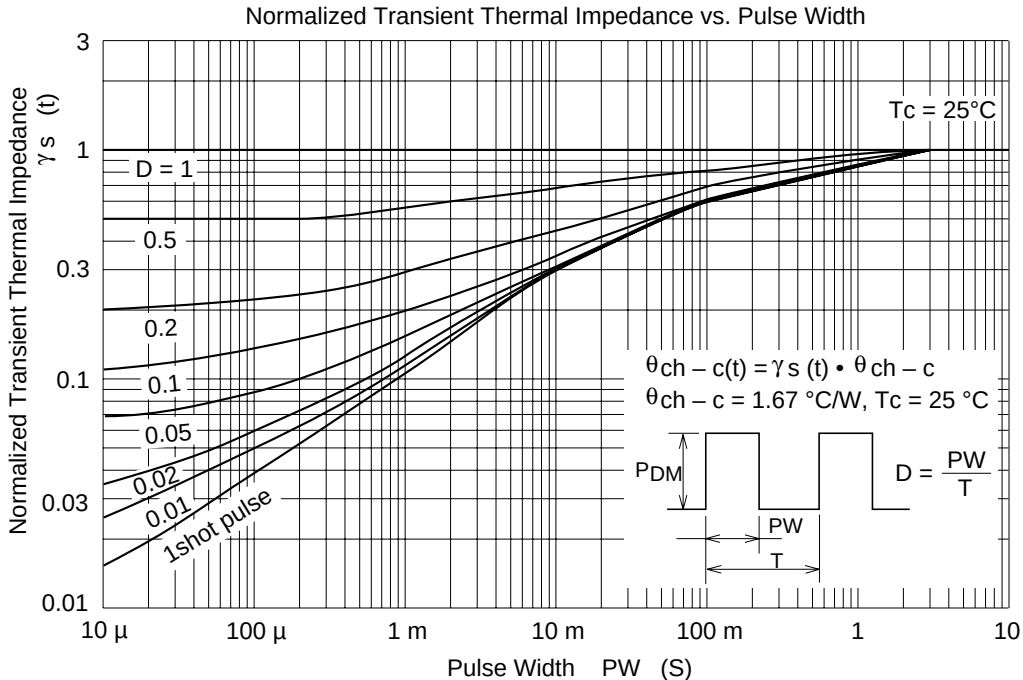
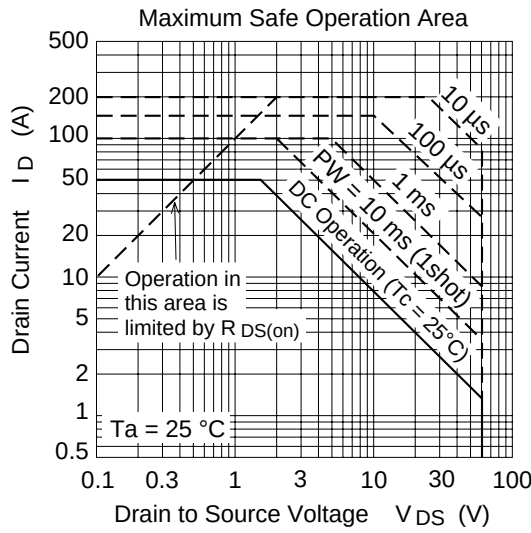
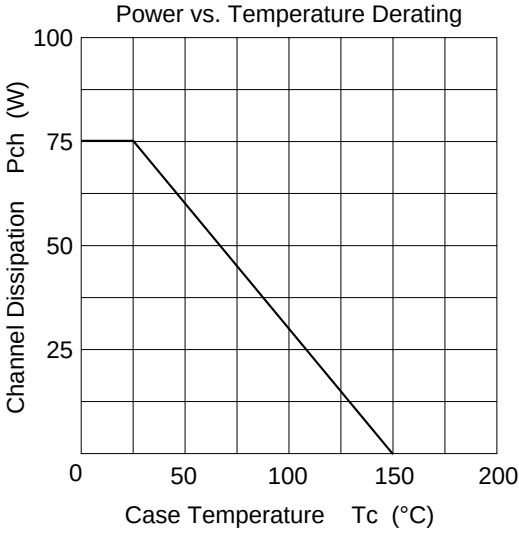
- Notes
- 1. PW ≤ 10 μs, duty cycle ≤ 1 %
  - 2. Value at Tc = 25°C
  - 3. Value at Tch = 25°C, Rg ≥ 50 Ω

**Electrical Characteristics** (Ta = 25°C)

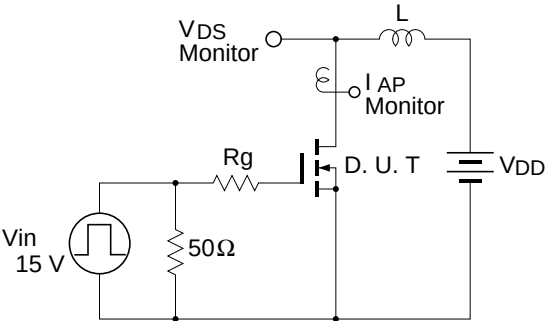
| Item                                       | Symbol        | Min | Typ  | Max | Unit | Test Conditions                                                                 |
|--------------------------------------------|---------------|-----|------|-----|------|---------------------------------------------------------------------------------|
| Drain to source breakdown voltage          | $V_{(BR)DSS}$ | 60  | —    | —   | V    | $I_D = 10 \text{ mA}$ , $V_{GS} = 0$                                            |
| Gate to source breakdown voltage           | $V_{(BR)GSS}$ | ±20 | —    | —   | V    | $I_G = \pm 100 \text{ } \mu\text{A}$ , $V_{DS} = 0$                             |
| Gate to source leak current                | $I_{GSS}$     | —   | —    | ±10 | μA   | $V_{GS} = \pm 16 \text{ V}$ , $V_{DS} = 0$                                      |
| Zero gate voltage drain current            | $I_{DSS}$     | —   | —    | 10  | μA   | $V_{DS} = 60 \text{ V}$ , $V_{GS} = 0$                                          |
| Gate to source cutoff voltage              | $V_{GS(off)}$ | 1.0 | —    | 2.0 | V    | $I_D = 1 \text{ mA}$ , $V_{DS} = 10 \text{ V}$                                  |
| Static drain to source on state resistance | $R_{DS(on)}$  | —   | 7    | 10  | mΩ   | $I_D = 25 \text{ A}$<br>$V_{GS} = 10 \text{ V}$ <sup>Note 1</sup>               |
|                                            |               | —   | 10   | 16  | mΩ   | $I_D = 25 \text{ A}$<br>$V_{GS} = 4 \text{ V}$ <sup>Note 1</sup>                |
| Forward transfer admittance                | $ y_{fs} $    | 35  | 55   | —   | S    | $I_D = 25 \text{ A}$<br>$V_{DS} = 10 \text{ V}$ <sup>Note 1</sup>               |
| Input capacitance                          | $C_{iss}$     | —   | 3550 | —   | pF   | $V_{DS} = 10 \text{ V}$                                                         |
| Output capacitance                         | $C_{oss}$     | —   | 1760 | —   | pF   | $V_{GS} = 0$                                                                    |
| Reverse transfer capacitance               | $C_{rss}$     | —   | 500  | —   | pF   | $f = 1 \text{ MHz}$                                                             |
| Turn-on delay time                         | $t_{d(on)}$   | —   | 35   | —   | ns   | $I_D = 25 \text{ A}$                                                            |
| Rise time                                  | $t_r$         | —   | 230  | —   | ns   | $V_{GS} = 10 \text{ V}$                                                         |
| Turn-off delay time                        | $t_{d(off)}$  | —   | 470  | —   | ns   | $R_L = 1.2 \text{ } \Omega$                                                     |
| Fall time                                  | $t_f$         | —   | 360  | —   | ns   |                                                                                 |
| Body to drain diode forward voltage        | $V_{DF}$      | —   | 0.85 | —   | V    | $I_F = 50 \text{ A}$ , $V_{GS} = 0$                                             |
| Body to drain diode reverse recovery time  | $t_{rr}$      | —   | 135  | —   | ns   | $I_F = 50 \text{ A}$ , $V_{GS} = 0$<br>$di_F / dt = 50 \text{ A} / \mu\text{s}$ |

Note 1. Pulse Test

See characteristic curves of 2SK2529.

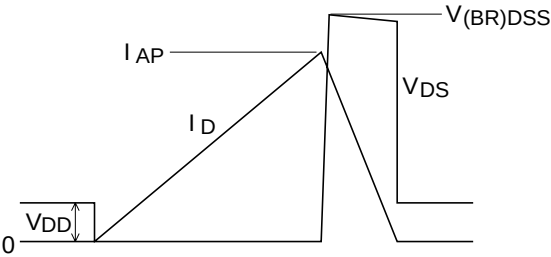


Avalanche Test Circuit

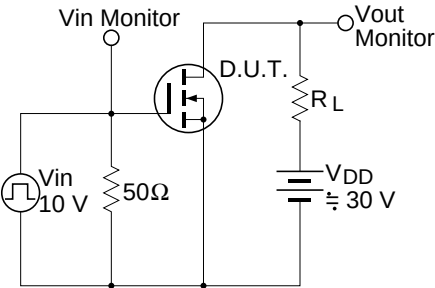


Avalanche Waveform

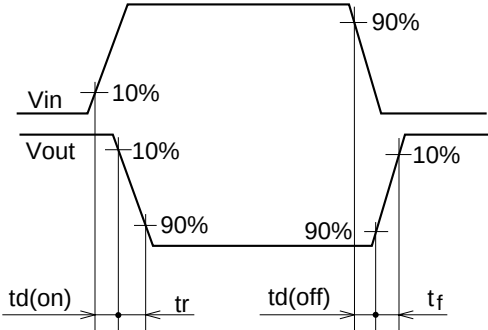
$$E_{AR} = \frac{1}{2} \cdot L \cdot I_{AP}^2 \cdot \frac{V_{DSS}}{V_{DSS} - V_{DD}}$$



Switching Time Test Circuit

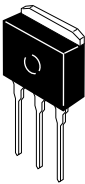
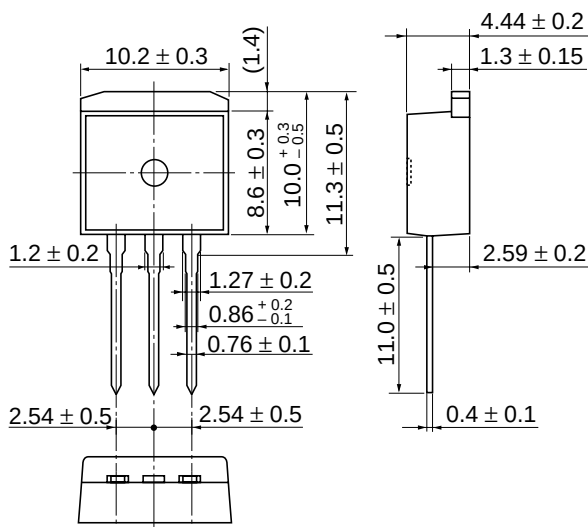


Waveform



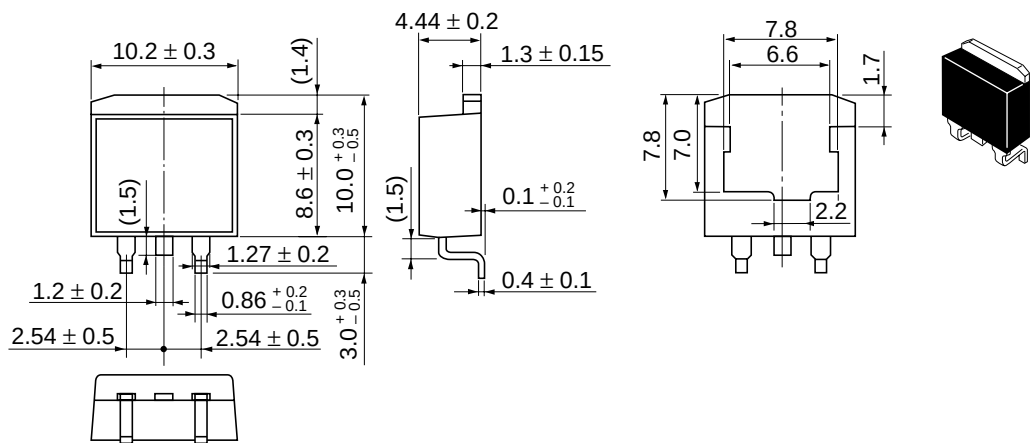
Package Dimensions

As of January, 2001  
Unit: mm



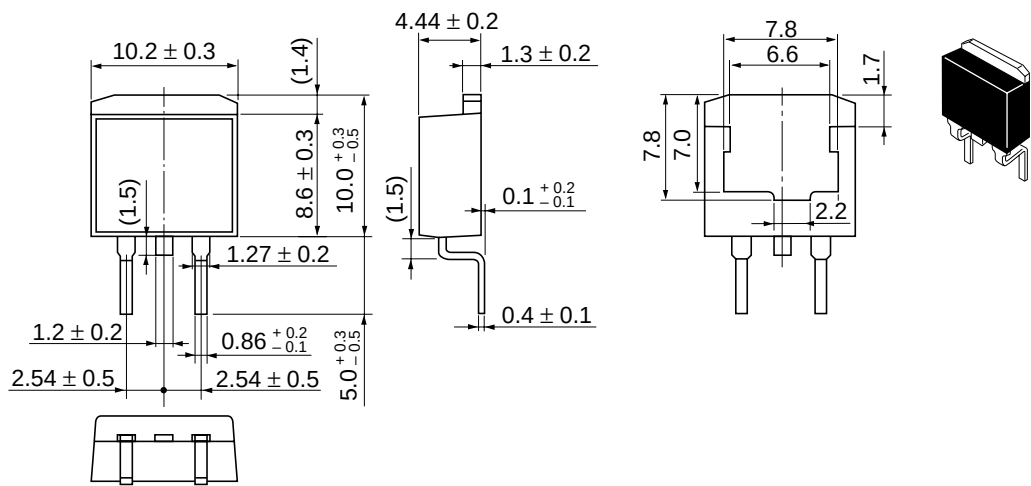
|                        |           |
|------------------------|-----------|
| Hitachi Code           | LDBAK (L) |
| JEDEC                  | —         |
| EIAJ                   | —         |
| Mass (reference value) | 1.4 g     |

As of January, 2001  
Unit: mm



|                        |               |
|------------------------|---------------|
| Hitachi Code           | LDBAK (S)-(1) |
| JEDEC                  | —             |
| EIAJ                   | —             |
| Mass (reference value) | 1.3 g         |

As of January, 2001  
Unit: mm



|                        |               |
|------------------------|---------------|
| Hitachi Code           | LDPAK (S)-(2) |
| JEDEC                  | —             |
| EIAJ                   | —             |
| Mass (reference value) | 1.35 g        |



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